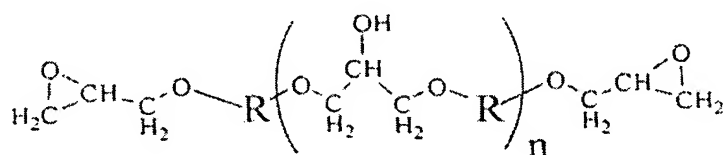


This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended): A process for production of a high-purity epoxy compound with total chlorine content of less than 500 ppm, said process comprising:
~~reacting characterized in that an epoxy compound according to represented~~
~~by the following general formula (I):~~

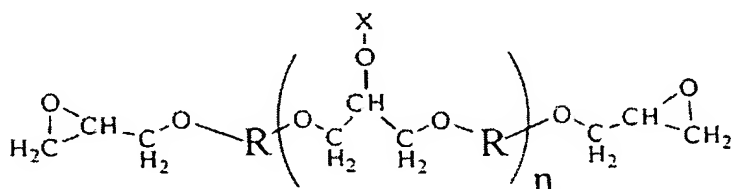


[[()]]wherein,

R represents a dihydric phenol compound residue and/or a dihydric alcohol compound residue, [[;]] and

n represents a numerical value with the average greater than 0 and not greater than 10 [[()]], in which the proportion of the component having n equal to 0 is more than 70% and less than 100%,

~~is caused to react~~ in the presence of alkali metal hydroxide at temperature of 95°C - 150°C ~~95°C - 150°C~~, to produce an epoxy compound according to represented by the
~~following general formula (II):~~



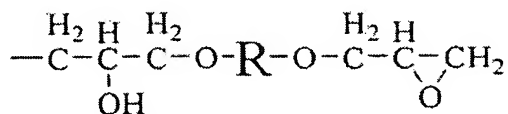
{wherein,

R represents a dihydric phenol compound residue and/or a dihydric alcohol compound

residue, [[:]]

n represents a numerical value with the average greater than 0 and not greater than 10, [[:]] and

X is a hydrogen atom or a group according to ~~represented by the following general formula (III):~~



[[:]]wherein,

R has the above-described meaning }, in

which the component with X represented by ~~the general formula (III)~~ is always contained.

2. (Currently Amended): A process ~~for production of a high-purity epoxy compound~~ according to claim 1, wherein the resultant manufactured epoxy compound obtained by the process contains ~~consists of the epoxy compound of represented by the general formula (I)~~ in the proportion of not less than 90% and less than 100%, and the epoxy compound of ~~represented by the general formula (II)~~ in the proportion of greater than 0% and not greater than 10%.

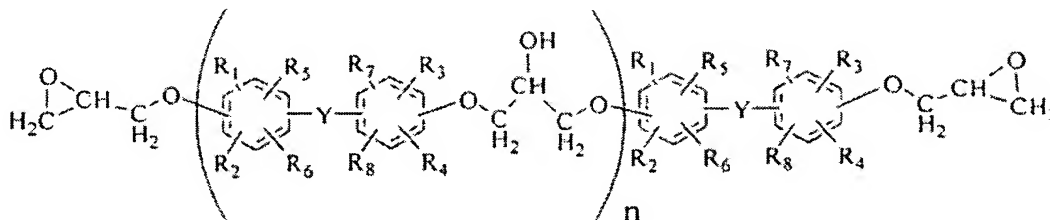
3. (Currently Amended): A process ~~for production of a high-purity epoxy compound~~ according to claim 1, wherein said alkali metal hydroxide is potassium hydroxide.

4. (Currently Amended): A process ~~for production of a high-purity epoxy compound~~ according to Claim 1, wherein 5-100 ~~5-100~~ g of potassium hydroxide is used per 1 kg of said the epoxy compound of resin represented by said general formula (I), and is used in the reaction in the form of aqueous solution of potassium hydroxide of 80% or higher in concentration.

5. (Currently Amended): A process ~~for production of a high-purity epoxy compound~~ according to Claim 1, wherein the reaction is conducted in the presence of a

tertiary alcohol.

6. (Currently Amended): A process for ~~production of a high purity epoxy compound~~ according to Claim 1, wherein said epoxy compound ~~of~~ represented by the ~~general formula (I)~~ is an epoxy compound according to ~~represented by the following general formula (IV):~~



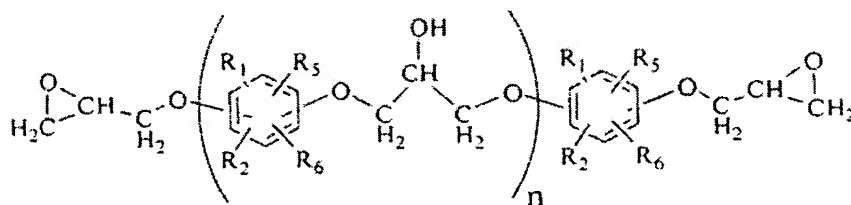
{wherein,

~~R₁-R₈~~ ~~R₁-R₈~~ may be same or different, and each of ~~R₁-R₈~~ ~~R₁-R₈~~ is a hydrogen, alkyl, allyl, phenyl group or halogen atom, [[:]]

Y represents a direct bond, ~~or~~ alkyl group with carbon number of ~~1 - 20~~ ~~1-20~~, allyl, phenyl, aralkyl, biphenylaralkyl, oxygen, sulphur, sulfone, or carboxyl group; and

n is a numerical value with average greater than 0 and not greater than 10; }

and /or an epoxy compound according to ~~represented by the following general formula (V):~~



{wherein,

R₁, R₂, R₅, and R₆ represent hydrogen, alkyl, allyl, phenyl group, or halogen atom, and may be same or different; [[:]] and

n is a numerical value with average greater than 0 and not greater than 10}.

7. (Currently Amended): A process for ~~production of a high-purity epoxy compound~~ according to Claim ~~6~~ 4, wherein said epoxy compound ~~of represented by the general formula (IV)~~ is a tetramethyl bisphenol type epoxy resin or a tetramethyl biphenyl type epoxy resin

8. (Currently Amended): A high purity epoxy resin composition ~~which contains, as essential components,~~ comprising the high-purity epoxy compound obtained by the process manufacturing method according to Claim 1, and a curing agent for epoxy resins.

9. (Currently Amended): A method of sealing electronic components comprising sealing said electronic parts using a A high purity epoxy resin composition according to claim 7 ~~for use as sealing material for electronic parts, which contains, as essential components, the high-purity epoxy compound obtained by the manufacturing method according to Claim 1 and a curing agent for epoxy resins.~~

10. (Currently Amended): A hardened epoxy resin product ~~which is~~ obtained by curing the epoxy resin composition according to claim 8.

11. (New): A process according to claim 1, wherein the resultant epoxy compound obtained by the process has a total chlorine content of less than 350 ppm.

12. (New): A process according to claim 1, wherein, for the epoxy of the compound of Formula (I) that is to be reacted, the proportion of the epoxy compound having n equal to 0 is 70% -99%.

13. (New): A process according to claim 1, wherein, for the epoxy of the compound of Formula (I) that is to be reacted, the proportion of the epoxy compound having n equal to 0 is 80% -99%.

14. (New): A process according to claim 2, wherein the resultant epoxy compound obtained by the process contains the epoxy compound of formula (II) in an

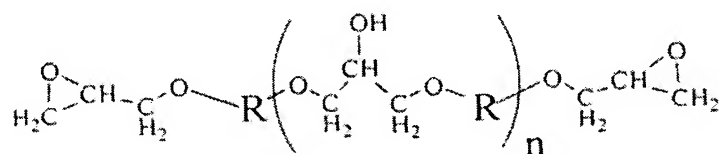
amount of 1-10%.

15. (New): A process according to claim 14, wherein the resultant epoxy compound obtained by the process contains the epoxy compound of formula (II) in an amount of 1-6%.

16. (New): A process according to claim 15, wherein the resultant epoxy compound obtained by the process contains the epoxy compound of formula (II) in an amount of 2-5%.

17. (New): A process for production of a high-purity epoxy composition with total chlorine content of less than 500 ppm, said process comprising:

reacting a first component of epoxy compounds according to formula (I)

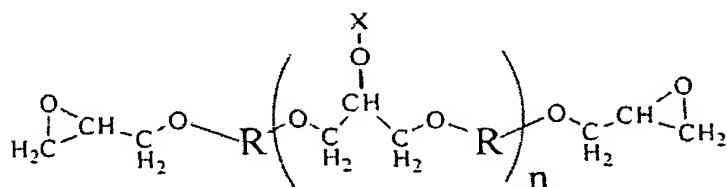


wherein,

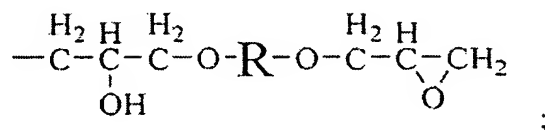
R is a dihydric phenol compound residue and/or a dihydric alcohol compound residue,
and

n is a numerical value wherein the average value for n for said first component is greater than 0 and not greater than 10, and the proportion of said first component made up of compounds of formula I having n equal to 0 is more than 70% and less than 100%,

in the presence of alkali metal hydroxide at temperature of 95°C - 150°C, to produce a second component of epoxy compounds according to formula (II):



wherein X is a hydrogen atom or a group according to formula (III);

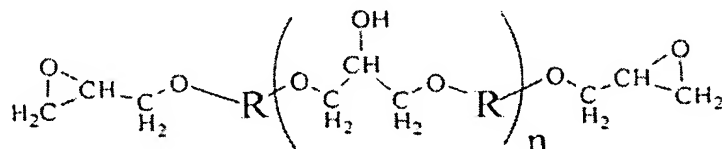


wherein the resultant epoxy composition contains epoxy compounds of formula (I) in a proportion of not less than 90% and less than 100%, and epoxy compounds of formula (II) in a proportion of greater than 0% and not greater than 10%, and

wherein said epoxy composition contains a component of epoxy compounds of formula II in which X is of formula (III).

18. (New): A high-purity epoxy compound, with total chlorine content of less than 500 ppm, obtained by a process comprising:

reacting an epoxy compound according to formula (I):

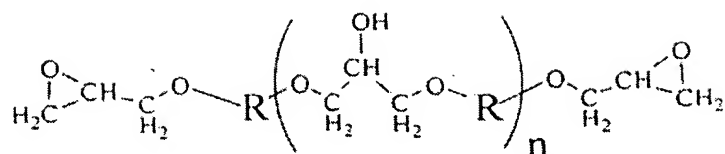


wherein,

R represents a dihydric phenol compound residue and/or a dihydric alcohol compound residue, and

n represents a numerical value with the average greater than 0 and not greater than 10, in which the proportion of the component having n equal to 0 is more than 70% and less than 100%,

in the presence of alkali metal hydroxide at temperature of 95°C - 150°C, to produce an epoxy compound according to formula (II):

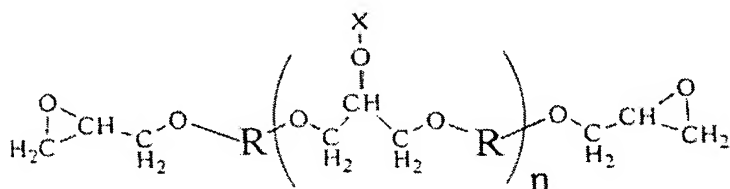


wherein,

R represents a dihydric phenol compound residue and/or a dihydric alcohol compound residue, and

n represents a numerical value with the average greater than 0 and not greater than 10, in which the proportion of the component having n equal to 0 is more than 70% and less than 100%,

in the presence of alkali metal hydroxide at temperature of 95°C - 150°C, to produce an epoxy compound according to formula (II):

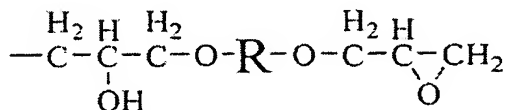


wherein,

R represents a dihydric phenol compound residue and/or a dihydric alcohol compound residue,

n represents a numerical value with the average greater than 0 and not greater than 10, and

X is a hydrogen atom or a group according to formula (III):



wherein,

R has the above-described meaning, in
which the component with X represented by formula (III) is always contained.